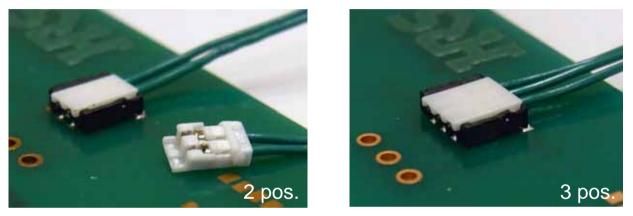
DF57 Series

1.2 mm Pitch, Low Profile "Swing Lock" Wire to Board Connector for Power Supply



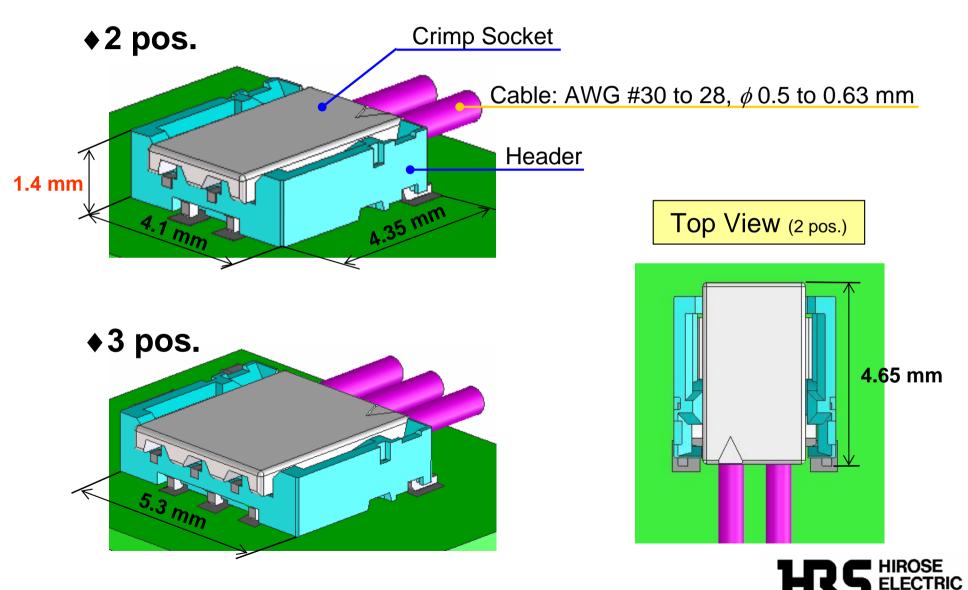
♦ Features

- 1. 1.2 mm pitch, 1.4 mm height, low profile connector
- 2. "Swing lock"; Both positive and friction locks are provided for cable pull force resistance

- 3. High current capability; 2.5 Amps (2 pos. with AWG#28 cable)
- 4. Solder wicking prevention
- 5. High contact lance strength
- 6. 0.5 to 0.63 mm dia., AWG#30 to 28 cable is applicable
- 7. RoHS compliant



1.2 mm Pitch, Low Profile Connector



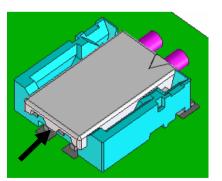
Specifications herein are subject to change without notice. Contact Hirose for latest specifications, drawings, or availabilities.



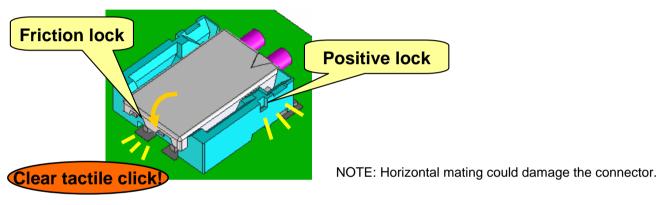
*Swing Lock" *Hirose's unique double lock design

Mating Operation

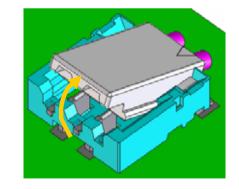
- 1. Insert the cable side first.
- **Unmating Operation**
 - 1. Hook the lever.



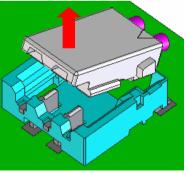
2. Press down at the lever side.



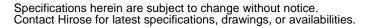
2. Pull up and friction lock is released.



3. Positive lock is released and removal completes.



Two locks, positive lock and friction lock are provided in this small connector.

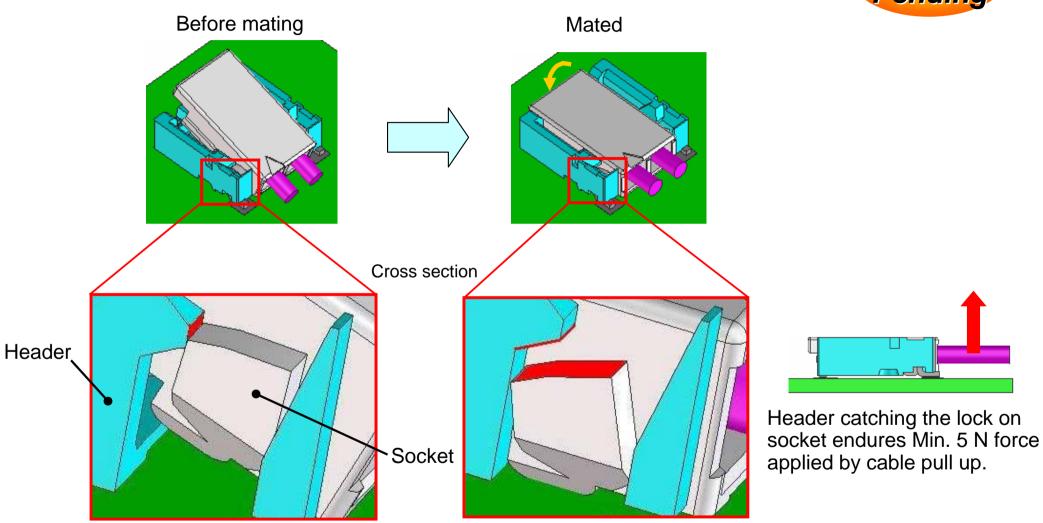






Positive Lock Structure





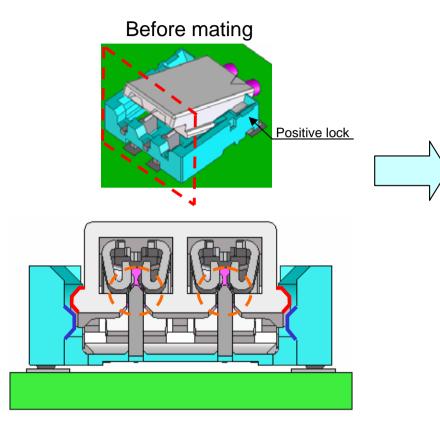
Accidental socket removal by cable pull is avoidable.

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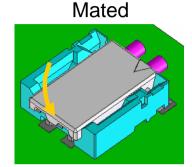


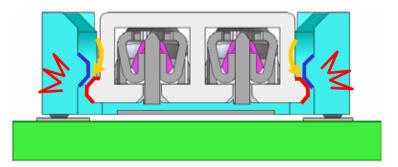


Friction Lock Structure



-Just inserting the positive lock does not conduct electricity for safety.





- -Sudden decline of load toward mating direction generates clear click feeling, preventing incomplete lock.
- -Friction lock prevents the socket from floating after mated.



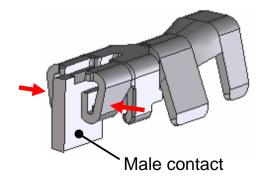
DF57 Contact Features

Long effective mating length Molded in contacts prevents solder wicking

No clearance between housing and the contacts, avoiding solder wicking.

High current capability

Rated Current for 2 pos. with AWG#28 cable: 2.5 Amps



-Controlled contact force decreases contact resistance, achieving high current capability

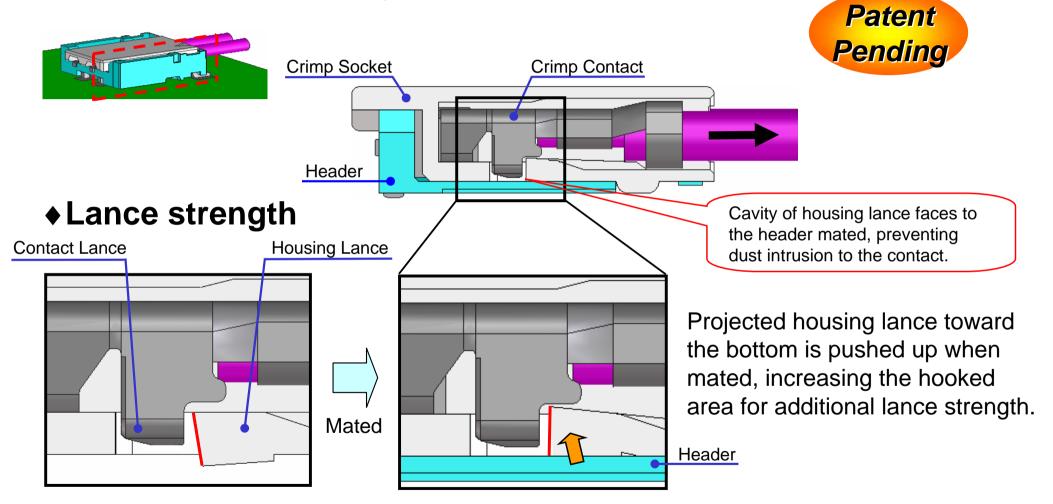
-Blade male contact is hard to deform

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Lance Structure

Lance is provided to the socket bottom.



 \rightarrow High lance strength prevents contact pulling loose during wiring.

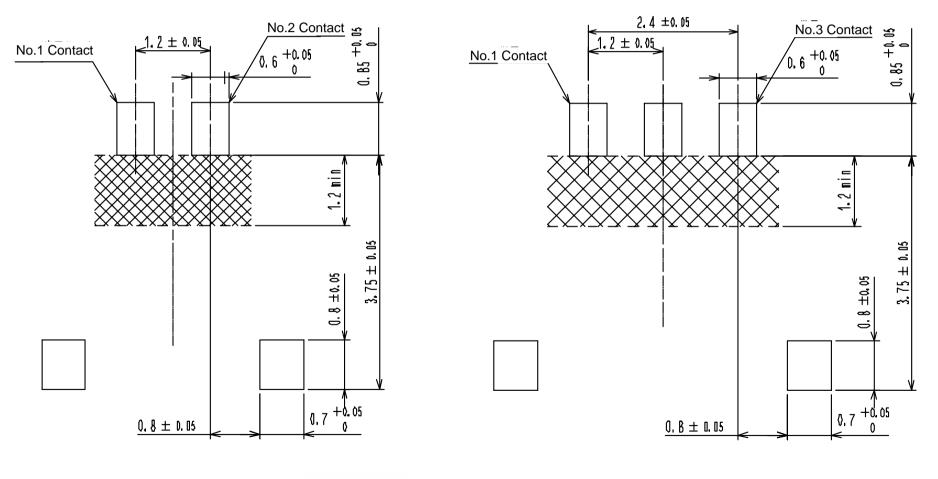


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Recommended PCB Layout

♦2 pos.

*****3 pos.



NOTES **No conductive trace.**



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Application Example



Modules

- -LED module
- -Touch panel
- -Small sized battery
- -Small sized motor
- -Vibrator etc.

Notebook PC



Industrial Robot

Digital Camera











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Specifications

Material and Finish

| COMPONENT | | MATERIAL | FINISH / REMARKS |
|----------------|--------|-----------------|--------------------------------------|
| Housing | Header | LCP | UL94V-0, Black |
| | Socket | PBT | UL94V-0, White |
| Header Contact | | Brass | Tin-plated over Nickel under plating |
| Crimp Contact | | Phosphor bronze | Tin-plated |
| Metal Fitting | | Brass | Tin-plated over Nickel under plating |

Performance Characteristics

| Rated Current | 2 pos. AWG#28: 2.5 Amps, AWG#30: 1.5 Amps | |
|--|--|--|
| Raleu Curreni | 3 pos. AWG#28: 2.0 Amps, AWG#30: 1.5 Amps | |
| Rated Voltage | 50 V AC / DC | |
| Operating Temperature | - 35 °C to + 85 °C | |
| Contact Resistance | 10 m Ω MAX. at 20 mV, 1 mA | |
| Insulation Resistance | sulation Resistance 100 M Ω MIN. (100 V DC) | |
| Vithstanding Voltage 500 V AC for 1 minute | | |
| Applicable Cable | AWG#28 to 30, \$\$\phi\$ 0.5 to 0.63 mm | |
| Durability | 30 cycles (Insertion / Withdrawal) | |

♦ Varieties

2 and 3 pos. (4 pos. is under development. 5 and 6 pos. is under study.)

